

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/04/2022

Details for "OMAP5910IGDY2"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
OMAP5910IGDY2	SNPB	Level-3-220C-168 HR	TI PHILIPPINES A/T	GDY 289	19x19x1.78	1345.7

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
No	Affected	Yes	Affected

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	2.328191	97.585747	975857	0.173005	1730
Nickel and Its Alloys	Nickel	7440-02-0	0.000012	0.000503	5	0.000001	0
Not Categorized	Proprietary Materials		0.000262	0.010982	110	0.000019	0
Precious Metals	Palladium	7440-05-3	0.057256	2.399876	23999	0.004255	43
Precious Metals	Silver	7440-22-4	0.000069	0.002892	29	0.000005	0
Sub-Total			2.38579	100	1000000	0.177286	1773
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	9.113345	82.000003	820000	0.677203	6772
Thermoplastics	Epoxy	85954-11-6	2.00049	17.999997	180000	0.148654	1487
Sub-Total			11.113835	100	1000000	0.825857	8259
Mold Compound							
Aluminum and Its Alloys	Alumina	1344-28-1	6.81275	1	10000	0.506248	5062
Other Inorganic Materials	Fused Silica	60676-86-0	599.521974	88	880000	44.549853	445499
Other Plastics and Rubber	Carbon Black	1333-86-4	3.406375	0.5	5000	0.253124	2531
Thermoplastics	Epoxy	85954-11-6	71.533872	10.5	105000	5.315607	53156
Sub-Total			681.274971	100	1000000	50.624833	506248
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	34.927971	100	1000000	2.595461	25955
Sub-Total			34.927971	100	1000000	2.595461	25955
Solder Ball							
Other Nonferrous Metals and Alloys	Antimony	7440-36-0	0.828501	0.5	5000	0.061565	616
Other Nonferrous Metals and Alloys	Lead	7439-92-1	57.149972	34.49	344900	4.246755	42468
Other Nonferrous Metals and Alloys	Tin	7440-31-5	104.407647	63.01	630100	7.758423	77584
Precious Metals	Silver	7440-22-4	3.314002	2	20000	0.24626	2463
Sub-Total			165.700122	100	1000000	12.313003	123130
Substrate							
Ceramics / Glass	Woven Glass Fiber	65997-17-3	170.573611	37.877463	378775	12.675147	126751
Copper and Its Alloys	Copper	7440-50-8	74.369568	16.514457	165145	5.526325	55263
Nickel and Its Alloys	Nickel	7440-02-0	4.385043	0.97374	9737	0.325848	3258
Not Categorized	Proprietary Filler		2.764441	0.61387	6139	0.205423	2054
Other Inorganic Materials	Silica	7631-86-9	2.764441	0.61387	6139	0.205423	2054
Other Nonferrous Metals and Alloys	Barium Sulfate	7727-43-7	2.764441	0.61387	6139	0.205423	2054
Other Plastics and Rubber	Phthalocyanine Blue	147-14-8	0.090156	0.02002	200	0.006699	67
Precious Metals	Gold	7440-57-5	0.380033	0.08439	844	0.02824	282
Thermoplastics	Epoxy	85954-11-6	192.238356	42.688321	426883	14.285032	142850
Sub-Total			450.33009	100	1000000	33.46356	334636
Total			1345.732779			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology.](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szsq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.